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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/598,515	09/01/2006	Seiichi Akagi	MIYOSH0008	6701
24203 GRIFFIN & SZ	7590 08/13/201 ¹ IPL, PC	EXAMINER		
SUITE PH-1	,	PAK, HANNAH J		
2300 NINTH STREET, SOUTH ARLINGTON, VA 22204			ART UNIT	PAPER NUMBER
			1796	
			MAIL DATE	DELIVERY MODE
			08/13/2010	PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

	Application No.	Applicant(s)				
Decrease to Dule 242 Communication	10/598,515	AKAGI ET AL.				
Response to Rule 312 Communication	Examiner	Art Unit				
	Hannah Pak	1796				
The MAILING DATE of this communication a	ppears on the cover shee	t with the correspondence address –				
1. ☑ The amendment filed on 23 July 2010 under 37 CFR 1.3	312 has been considered, a	nd has been:				
a) 🛛 entered.						
b) entered as directed to matters of form not affecting the scope of the invention.						
c) disapproved because the amendment was filed after the payment of the issue fee. Any amendment filed after the date the issue fee is paid must be accompanied by a petition under 37 CFR 1.313(c)(1) and the required fee to withdraw the application from issue.						
d) disapproved. See explanation below.						
e) 🔲 entered in part. See explanation below.						
a) The IDS filed 07/23/2010 is deemed to be proper for er with 37 CFR 1.97 and 1.98.	ntry since its compliance is e	established in accordance				
b) Initialed and signed IDS filed 07/23/2010 is attached. The attached IDS filed 07/23/2010 does not affect patentability because the cited references do not read on the instant claims. Specifically, JP 01-252-125 teaches an epoxy resin composition useful for producing resin-sealed semiconductor device comprising a curing agent, but fails to teach an epoxy resin defined by the claimed General Formula (I). Accordingly, the reasons for allowance mailed 07/23/2010 remains valid.						
/Vasu Jagannathan/ Supervisory Patent Examiner, Art Unit 1796	/Hannah Pak/ Examiner, Art Un	it 1796				